

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

ON Semiconductor®

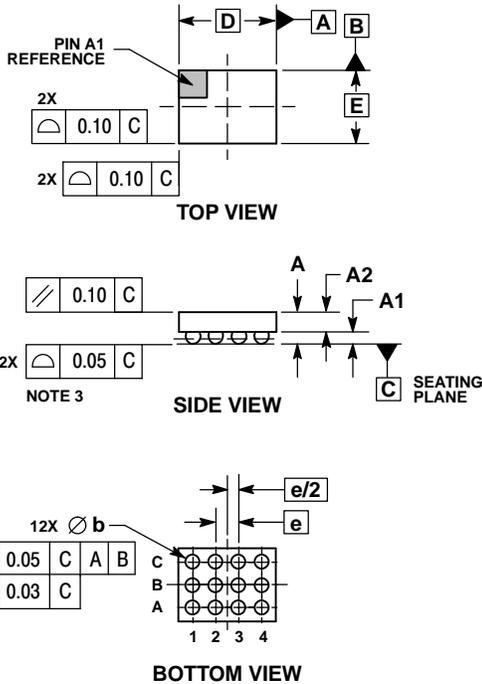


SCALE 4:1

### 12 PIN FLIP-CHIP, 1.62x1.22, 0.4P

CASE 499BJ  
ISSUE C

DATE 18 NOV 2015



**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

MILLIMETERS		
DIM	MIN	MAX
A	0.50	0.56
A1	0.17	0.23
A2	0.33	0.39
b	0.24	0.29
D	1.62 BSC	
E	1.22 BSC	
e	0.40 BSC	

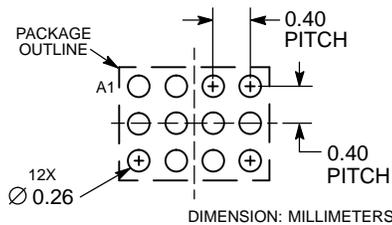
**GENERIC MARKING DIAGRAM\***



- XXXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- WW = Work Week
- = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "C" or microdot "▪", may or may not be present.

**RECOMMENDED SOLDERING FOOTPRINT**



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<b>STATUS:</b>	ON SEMICONDUCTOR STANDARD	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	12 PIN FLIP-CHIP, 1.62 X 1.22, 0.4P	<b>PAGE 1 OF 2</b>

